

General Description

The MAX696/MAX697 supervisory circuits reduce the complexity and number of components required for power-supply monitoring and battery-control functions in microprocessor (µP) systems. These include µP reset and backup-battery switchover, watchdog timer, CMOS RAM write protection, and power-failure warning. The MAX696/MAX697 significantly improve system reliability and accuracy compared to that obtained with separate ICs or discrete components.

The MAX696 and MAX697 are supplied in 16-pin packages and perform six functions:

- 1) A reset output during power-up, power-down, and brownout conditions. The threshold for this "lowline" reset is adjustable by an external voltage-
- 2) A reset pulse if the optional watchdog timer has not been toggled within a specified time.
- 3) Individual outputs for low-line and watchdog fault conditions.
- 4) The reset time may be left at its default value of 50ms, or may be varied with an external capacitor or clock pulses.
- 5) A separate 1.3V threshold detector for power-fail warning, low-battery detection, or to monitor a power supply other than Vcc.

The MAX696 also has battery-backup switching for CMOS RAM, CMOS microprocessor, or other lowpower logic.

The MAX697 lacks battery-backup switching, but has write-protection pins (CE IN and CE OUT) for CMOS RAM or EPROM. In addition, it consumes less than 250 microamperes.

Applications

Computers

Controllers

Intelligent Instruments

Automotive Systems

Critical µP Power Monitoring

Typical Operating Circuit appears at end of data sheet.

Pin Configurations continued at end of data sheet.

Features

- ♦ Adjustable Low-Line Monitor and Power-Down Reset
- ♦ Power-OK/Reset Time Delay
- ♦ Watchdog Timer—100ms, 1.6s, or Adjustable
- **♦ Minimum Component Count**
- ♦ 1µA Standby Current
- ♦ Battery-Backup Power Switching (MAX696)
- ♦ On-Board Gating of Chip-Enable Signals (MAX697)
- ♦ Separate Monitor for Power-Fail or Low-Battery Warning

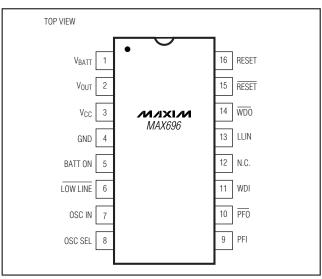
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX696C/D	0°C to +70°C	Dice
MAX696CPE	0°C to +70°C	16 PDIP
MAX696CWE	0°C to +70°C	16 Wide SO
MAX696EPE	-40°C to +85°C	16 PDIP
MAX696EJE	-40°C to +85°C	16 CERDIP
MAX696EWE	-40°C to +85°C	16 Wide SO
MAX696MJE	-55°C to +125°C	16 CERDIP

Ordering Information continued at end of data sheet.

Devices in PDIP and SO packages are available in both leaded and lead-free packaging. Specify lead free by adding the + symbol at the end of the part number when ordering. Lead free not available for CERDIP package.

Pin Configurations



MIXIM

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

Terminal Voltage (with respect to GND)	
V _C C	
VBATT	
All Other Inputs (Note 1)	0.3V to $(V_{OUT} + 0.5V)$
Input Current	
V _{CC}	200mA
VBATT	50mA
GND	20mA
Output Current	
Vout	Short-Circuit Protected
All Other Outputs	20mA

Rate-of-Rise, V _{BATT} , V _{CC}	100V/µs
Operating Temperature Range	
C Suffix	0°C to +70°C
E Suffix	40°C to +85°C
M Suffix	-55°C to +125°C
Power Dissipation ($T_A = +70^{\circ}C$)	
16-Pin PDIP (derated 7mW/°C above +70°C)	
16-Pin SO (derated 7mW/°C above +70°C)	600mW
16-Pin CERDIP (derated 10mW/°C above +8	5°C)600mW
Storage Temperature Range	-65°C to +160°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: The input voltage limits on PFI and WDI may be exceeded providing the input current is limited to less than 10mA.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VCC = full operating range, VBATT = 2.8V, TA = +25°C, unless otherwise noted.)

PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS
		MAX696 VC	C	3.0		5.5	
Operating Voltage Range	T _A = full	MAX696 VB	ATT	2.0		V _{CC} - 0.3V	V
		MAX697 VC	C	3.0		5.5	
Supply Current (MAX697)	T _A = full				160	300	μΑ
BATTERY-BACKUP SWITCHING	(MAX696)						
Varia Outrout Valtaga	IOUT = 1mA	x, $TA = full$		V _{CC} - 0.3	V _{CC} - 0.1		V
V _{OUT} Output Voltage	I _{OUT} = 50m	A, $T_A = full$		Vcc - 0.5	Vcc - 0.25		
V _{OUT} in Battery-Backup Mode	I _{OUT} = 250μA, V _{CC} < (V _{BATT} - 0.2V), T _A = full			V _{BATT} - 0.1	V _{BATT} - 0.02		V
Cupali Current (Evaludes I)	I _{OUT} = 1mA			1.5	4	- mA	
Supply Current (Excludes I _{OUT})	I _{OUT} = 50mA				2.5		7
Supply Current in Battery-Backup	V _{CC} = 0V, V	$I_{BATT} = 2.8V,$	$T_A = +25^{\circ}C$		0.6	1	μA
Mode	VCC = 0V, V	/BATT = 2.8V,	$T_A = full$			10	μΑ
Battery Standby Leakage Current	5.5V > V _{CC}	> (V _{BATT} +	$T_A = +25^{\circ}C$	-100		+20	nA
Battery Standby Leakage Current	0.3V)		$T_A = full$	-1.00		+0.02	μΑ
Battery Switchover Threshold	Power-up				70		mV
VCC - VBATT	Power-down	า			50		1110
Battery Switchover Hysteresis				20		mV	
BATT ON Output Voltage	I _{SINK} - 1.6mA					0.4	V
BATT ON Output Short-Circuit	BATT ON = V _{OUT} = 2.4V sink current			7		mA	
Current	BATT ON = V _{OUT} , V _{CC} = 0V			0.5	2.5	25.0	μΑ
RESET AND WATCHDOG TIMER							
Low-Line Voltage Threshold (LL _{IN})	$V_{CC} = +5V,$	$+3V$; $T_A = fu$	II	1.25	1.30	1.35	V

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = \text{full operating range}, V_{BATT} = 2.8V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNITS		
Reset Timeout Delay	Figure 6, OSC	SEL HIGH, V _{CC} = 5V	35	50	70	ms		
Watchdog Timeout Period,	Long period, V _{CC} = 5V		1.00	1.6	2.25	S		
Internal Oscillator	Short period, V	CC = 5V	70	100	140	ms		
Watchdog Timeout Period,	Long period		4032		4097	Clock		
External Clock	Short period		960		1025	cycles		
Minimum WDI Input Pulse Width	VII. = 0.4V, VIH	= 3.5V, V _{CC} = 5V	200			ns		
·		VCC = 2V, VBATT = 0V			0.4			
RESET and RESET Output		I _{SINK} = 1.6mA, 3V < V _{CC} < 5.5V			0.4	V		
Voltage (Note 2)	ISOURCE = 1µA		3.5			1		
LOW LINE and WDO Output	I _{SINK} = 800μA,				0.4			
Voltage		A , $V_{CC} = 5V$, $T_A = full$	3.5			V		
Output Short-Circuit Current		, WDO, LOW LINE	1	3	25	μA		
	112021,112021	Logic-low			0.8	Pr' t		
WDI Input Threshold	VCC = 5V	Logic-high (MAX696)	3.5		0.0	V		
Wat impat impondia	(Note 3)	Logic-high (MAX697)	3.8			1		
	WDI = V _{OUT}	Logic High (Will Most)	0.0	20	50			
WDI Input Current	WDI = 0V		-50	-15	30	μΑ		
POWER-FAIL DETECTOR	VVD1 = 0V		-30	-10				
PFI Input Threshold	V _{CC} = 3V, 5V		1.2	1.3	1.4	V		
PFI - LL _{IN} Threshold Difference	$V_{CC} = 3V, 5V$		1.2	±15	±50	mV		
PFI Input Current	00 - , -			±0.01	±25	nA		
11	MAX697	MAX697			+25	A		
LLIN Input Current	MAX696	-500	±0.01	+25	nA			
PFO Output Voltage	I _{SINK} = 1.6mA				0.4	V		
FFO Output Voltage	ISOURCE = 1µA	ISOURCE = 1µA, VCC = 5V				V		
PFO Short-Circuit Source Current	$PFI = 0V, \overline{PFO}$	1	3	25	μΑ			
CHIP-ENABLE GATING (MAX69	7)							
CE IN Thresholds	VIL	V _{IL}			8.0	V		
CE IIV TITIESTICIAS	V_{IH} , $V_{CC} = 5V$	V _{IH} , V _{CC} = 5V						
CE IN Pullup Current				3		μΑ		
	ISINK = 1.6mA				0.4			
						1		
CE OUT Output Voltage	ISOURCE = 800	ISOURCE = 800μA				V		
, 5								
	ISOURCE = 1µA	$A, V_{CC} = OV$	V _{CC} - 0.05V					
CE Propagation Delay	$V_{CC} = 5V$			80	150	ns		
OSCILLATOR	_ L		<u>I</u>			I.		
OSC IN Input Current				±2		μΑ		
OSC SEL Input Pullup Current				5		μΑ		
OSC IN Frequency Range	000 051 014		0		250	kHz		
Obb in Frequency Hange	OSC SEL = 0V							
OSC IN Frequency with External	OSC SEL = 0V			4		kHz		

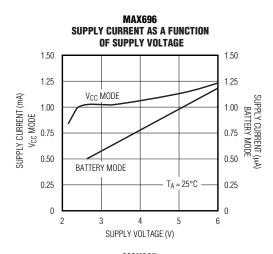
Note 2: T_A = full operating range.

Note 3: WDI is guaranteed to be in the mid-level (inactive) state if WDI is floating and V_{CC} is in the operating voltage range. WDI is internally biased to 38% of V_{CC} with an impedance of approximately $125k\Omega$.

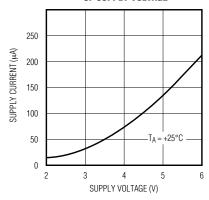


Typical Operating Characteristics

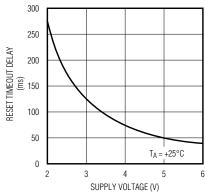
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$



MAX697 Supply Current as a function of Supply Voltage



RESET TIMEOUT DELAY AS A FUNCTION OF SUPPLY VOLTAGE



Pin Description

PIN		NASSE	EUNOTION		
MAX696	MAX697	NAME	FUNCTION		
1	-	VBATT	Backup-Battery Input. Connect to ground if a backup battery is not used.		
2	_	Vout	The higher of V_{CC} or V_{BATT} is internally switched to V_{OUT} . Connect V_{OUT} to V_{CC} if V_{OUT} and V_{BATT} are not used.		
3	3	Vcc	+5V Input		
4	5	GND	0V Ground Reference for All Signals		
5	_	BATT ON	BATT ON goes High when V_{OUT} is Internally Switched to the V_{BATT} Input. It goes low when V_{OUT} is internally switched to V_{CC} . The output typically sinks 7mA and can directly drive the base of an external pnp transistor to increase the output current above the 50mA rating of V_{OUT} .		
6	6	LOW LINE	LOW LINE goes Low when LL _{IN} Falls Below 1.3V. It returns high as soon as LL _{IN} rises above 1.3V. See Figure 5.		
7	7	OSC IN	OSC IN Sets the Reset Delay Timing and Watchdog Timeout Period when OSC SEL Floats or is Driven Low. The timing can also be adjusted by connecting an external capacitor to this pin. See Figure 7. When OSC SEL is high, OSC IN selects between fast and slow watchdog timeout periods		
8	8	OSC SEL	When OSC SEL is Unconnected or Driven High, the Internal Oscillator Sets the Ritime Delay and Watchdog Timeout Period. When OSC SEL is low, the external oscillator input, OSC IN, is enabled. OSC SEL has a 3µA internal pullup. See Tab		
9	9	PFI	PFI is the Noninverting Input to the Power-Fail Comparator. When PFI is less than 1.3V, PFO goes low. Connect PFI to GND or V _{OUT} when not used. See Figure 1.		
10	10	PFO	PFO is the Output of the Power-Fail Comparator. It goes low when PFI is less than 1.3V. The comparator is turned off and PFO goes low when V _{CC} is below V _{BATT} .		
11	11	WDI	The Watchdog Input, WDI, is a Three-Level Input. If WDI remains either high or lo for longer than the watchdog timeout period, RESET pulses low and WDO goes to the watchdog timer is disabled when WDI is left floating or is driven to mid-supple the timer resets with each transition at the watchdog timer input.		
12	2	N.C.	No Connection. Leave this pin open.		
13	4	LL _{IN}	Low-Line Input. LL _{IN} is the CMOS input to a comparator whose other input is a precision 1.3V reference. The output is LOW LINE and is also connected to the repulse generator. See Figure 2.		
14	14	WDO	The Watchdog Output, WDO, goes Low if WDI Remains either High or Low for Longer than the Watchdog Timeout Period. WDO is set high by the next transition at WDI. If WDI is unconnected or at mid-supply, WDO remains high. WDO also goes high when LOW LINE goes low.		
15	15	RESET	RESET goes Low whenever LL _{IN} Falls Below 1.3V or V _{CC} Falls Below the V _{BATT} Input Voltage. RESET remains low for 50ms after LL _{IN} goes above 1.3V. RESET also goes low for 50ms if the watchdog timer is enabled but not serviced within its timeout period. The RESET pulse width can be adjusted as shown in Table 1.		
16	16	RESET	RESET is an Active-High Output. It is the inverse of RESET.		



Pin Description (continued)

P	IN	NAME FUNCTION		
MAX696	MAX697	INAIVIE	FUNCTION	
_	1	TEST	Used During Maxim Manufacture Only. Always ground this pin.	
_	12	CE OUT	CE OUT goes low only when CE IN is low and LLIN is above 1.3V. See Figure 5.	
_	13	CE IN	The Input to the $\overline{\text{CE}}$ Gating Circuit. Connect to GND or V _{OUT} if not used.	

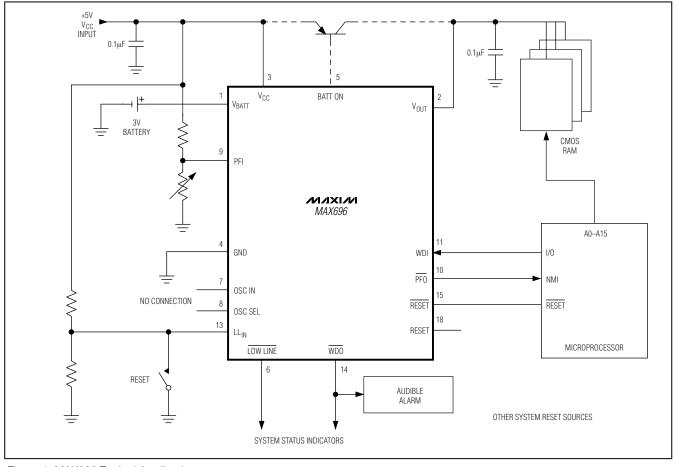


Figure 1. MAX696 Typical Application

Typical Applications

MAX696

A typical connection for the MAX696 is shown in Figure 1. CMOS RAM is powered from V_{OUT}. V_{OUT} is internally connected to V_{CC} when power is present, or to V_{BATT} when V_{CC} is less than the battery voltage. V_{OUT} can supply 50mA from V_{CC}, but if more current is required, an external pnp transistor can be added. When V_{CC} is higher than V_{BATT}, the BATT ON output goes low, providing

7mA of base drive for the external transistor. When VCC is lower than VBATT, an internal 200 Ω MOSFET connects the backup battery to VOUT. The quiescent current in the battery-backup mode is 1 μ A maximum when VCC is between 0V and (VBATT - 700mV).

Reset Output

A voltage detector monitors V_{CC} and generates a RESET output to hold the microprocessor's RESET line low when LL_{IN} is below 1.3V. An internal monostable holds RESET

low for 50ms after LL_{IN} rises above 1.3V. This prevents repeated toggling of \overline{RESET} even if the V_{CC} power drops out and recovers with each power line cycle.

The crystal oscillator normally used to generate the clock for microprocessors takes several milliseconds to start. Since most microprocessors need several clock cycles to reset, RESET must be held low until the microprocessor clock oscillator has started. The power-up RESET pulse lasts 50ms to allow for this oscillator startup time. An inverted, active-high RESET output is also supplied.

Power-Fail Detector

The MAX696 issues a nonmaskable interrupt (NMI) to the microprocessor when a power failure occurs. The power line is monitored by two external resistors connected to the power-fail input (PFI). When the voltage at PFI falls below 1.3V, the power-fail output (PFO) drives the processor's NMI input low. An earlier power-fail warning can be generated if the unregulated DC input of the regulator is available for monitoring.

Watchdog Timer

The microprocessor drives the watchdog input (WDI) with an I/O line. When OSC IN and OSC SEL are unconnected, the microprocessor must toggle the WDI pin once every 1.6 seconds to verify proper software execution. If a hardware or software failure occurs so that WDI is not toggled, the MAX696 will issue a 50ms RESET pulse after 1.6 seconds. This typically restarts the microprocessor's power-up routine. A new RESET pulse is issued every 1.6 seconds until WDI is again strobed.

The watchdog output (WDO) goes low if the watchdog timer is not serviced within its timeout period. Once WDO goes low, it remains low until a transition occurs at WDI while RESET is high. The watchdog timer feature can be disabled by leaving WDI unconnected. OSC IN and OSC SEL also allow other watchdog timing options, as shown in Table 1 and Figure 7.

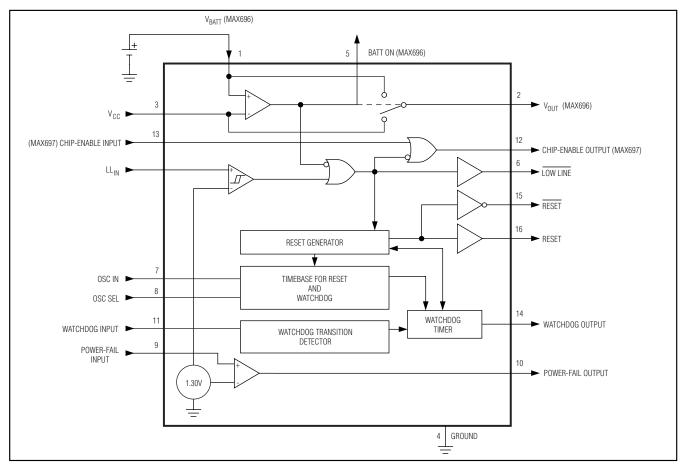


Figure 2. MAX696/MAX697 Block Diagram

MAX697

The MAX697 is nearly identical to the MAX696. The MAX697 lacks the battery-backup feature, so it does not have the VBATT, VOUT, or BATT ON pins. This allows the MAX697 to consume less than 250 microamperes, and it allows the inclusion of RAM write-protection pins. See Figure 2.

Detailed Description

Battery Switchover and Vout (MAX696)

The battery-switchover circuit compares $V_{\rm CC}$ to the VBATT input, and connects $V_{\rm OUT}$ to whichever is higher. Switchover occurs when $V_{\rm CC}$ is 50mV greater than VBATT as $V_{\rm CC}$ falls, and when $V_{\rm CC}$ is 70mV more than VBATT as $V_{\rm CC}$ rises (see Figure 3). The switchover comparator has 20mV of hysteresis to prevent repeated, rapid switching if $V_{\rm CC}$ falls very slowly or remains nearly equal to the battery voltage.

When V_{CC} is higher than V_{BATT} , V_{CC} is internally switched to V_{OUT} with a low-saturation pnp transistor. V_{OUT} has 50mA output current capability. Use an external pnp pass transistor in parallel with the internal transistor if the out-

put current requirement at V_{OUT} exceeds 50mA or if a lower V_{CC} - V_{OUT} voltage differential is desired. The BATT ON output can directly drive the base of the external transistor.

It should be noted that the MAX696 need only supply the average current drawn by the CMOS RAM if there is adequate filtering. Many RAM data sheets specify a 75mA maximum supply current, but this peak current spike lasts only 100ns. A 0.1µF bypass capacitor at VOUT supplies the high instantaneous current, while VOUT need only supply the average load current, which is much less. A capacitance of 0.1µF or greater must be connected to the VOUT terminal to ensure stability.

A 200 Ω MOSFET connects the V_{BATT} input to V_{OUT} during battery backup. This MOSFET has very low input-to-output differential (dropout voltage) at the low current levels required for battery backup of CMOS RAM or other low-power CMOS circuitry. When V_{CC} equals V_{BATT}, the supply current is typically 12 μ A. When V_{CC} is between 0V and (V_{BATT} - 700mV), the typical supply current is only 600nA (typ), 1 μ A (max).

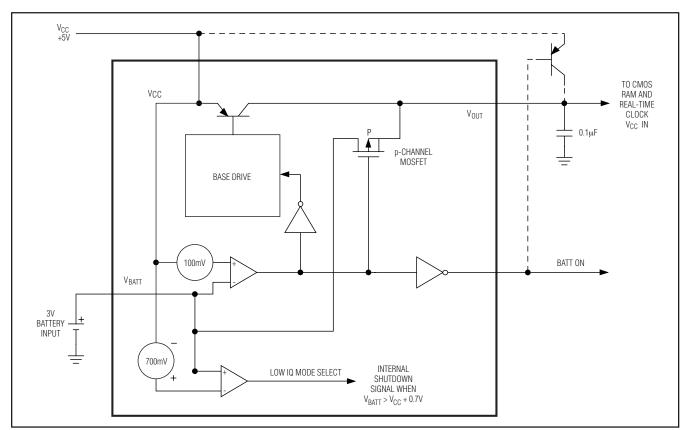


Figure 3. MAX696 Battery-Switchover Block Diagram

The MAX696 operates with battery voltages from 2.0V to 4.25V. The battery voltage should not be within 0.5V of VCC, or switchover may occur. High-value capacitors, either standard electrolytic or the farad-size double-layer capacitors, can also be used for short-term memory backup. The capacitor charging voltage should include a diode to limit the fully charged voltage to approximately 0.5V less than VCC. The charging resistor for rechargeable batteries should be connected to VOUT since this eliminates the discharge path that exists if the resistor is connected to VCC.

A small leakage current of typically 10nA (20nA max) flows out of the VBATT terminal. This current varies with the amount of current that is drawn from VOUT, but its polarity is such that the backup battery is always slightly charged, and is never discharged while VCC is in its operating voltage range. This extends the shelf life of the backup battery by compensating for its self-discharge current. Also note that this current poses no problem when lithium batteries are used for backup since the maximum current (20nA) is safe for even the smallest lithium cells.

If the battery-switchover section is not used, connect VBATT to GND and connect VOUT to VCC. Table 2 shows the state of the inputs and output in the low-power battery-backup mode.

Reset Output

RESET is an active-low output that goes low whenever LL_{IN} falls below 1.3V. It remains low until LL_{IN} rises above 1.312V for 50ms. (See Figures 4 and 5.)

The guaranteed minimum and maximum low-line thresholds of the MAX696/MAX697 are 1.2V and 1.4V. The LL_{IN} comparator has approximately 12mV of hysteresis.

The response time of the reset voltage comparator is about 100µs. LL_{IN} should be bypassed to ensure that glitches do not activate the RESET output.

RESET also goes low if the watchdog timer is enabled and WDI remains either high or low longer than the watchdog timeout period. RESET has an internal 3µA pullup, and can either connect to an open-collector reset bus or directly drive a CMOS gate without an external pullup resistor.

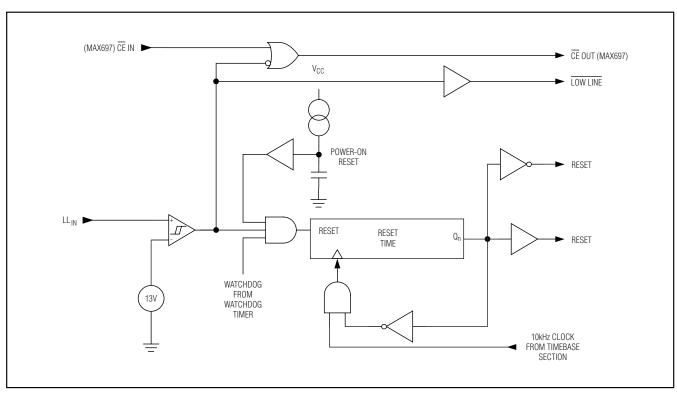


Figure 4. Reset Block Diagram

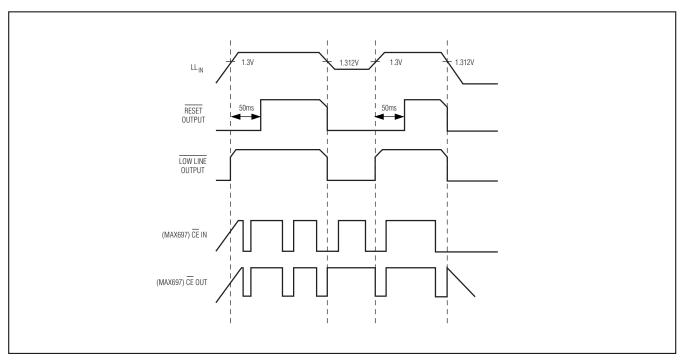


Figure 5. MAX697 Reset Timing

CE Gating and RAM Write Protection

The MAX697 uses two pins to control the $\overline{\text{CE}}$ or $\overline{\text{WRITE}}$ inputs of CMOS RAMs. When LL_{IN} is > 1.3V, $\overline{\text{CE}}$ OUT is a buffered replica of $\overline{\text{CE}}$ IN, with a 50ns propagation delay. If LL_{IN} input falls below 1.3V (1.2V min, 1.4V max), an internal gate forces $\overline{\text{CE}}$ OUT high, independent of $\overline{\text{CE}}$ IN. The $\overline{\text{CE}}$ output is also forced high when VCC is less than VBATT. (See Figure 4.)

CE OUT typically drives the $\overline{\text{CE}}$, $\overline{\text{CS}}$, or $\overline{\text{WRITE}}$ input of battery backed up CMOS RAM. This ensures the integrity of the data in memory by preventing write operations when V_{CC} is at an invalid level. Similar protection of EEPROMs can be achieved by using the $\overline{\text{CE}}$ OUT to drive the $\overline{\text{STORE}}$ or $\overline{\text{WRITE}}$ inputs of an EEPROM, EAROM, or NOVRAM.

If the 50ns typical propagation delay of $\overline{\text{CE}}$ OUT is too long, connect $\overline{\text{CE}}$ IN to GND and use the resulting $\overline{\text{CE}}$ OUT to control a high-speed external logic gate. A second alternative is to AND the $\overline{\text{LOW LINE}}$ output with the $\overline{\text{CE}}$ or $\overline{\text{WR}}$ signal. An external logic gate and the $\overline{\text{RESET}}$ output of the MAX696/MAX697 can also be used for CMOS RAM write protection.

1.25V Comparator and Power-Fail Warning

The power-fail input (PFI) is compared to an internal 1.3V reference. The power-fail output (PFO) goes low when the voltage at PFI is less than 1.3V. Typically PFI is driven bay an external voltage-divider that senses either the unregulated DC input to the system's VCC regulator or the regulated output. The voltage-divider ration can be chosen so the voltage at PFI falls below 1.3V several milliseconds before the LLIN falls below 1.3V. PFO is normally used to interrupt the microprocessor so that data can be stored in RAM before LLIN falls below 1.3V and the RESET output goes low.

The power-fail detector can also monitor the backup battery to warn of a low-battery condition. To conserve battery power, the power-fail detector comparator is turned off and PFO is forced low when VCC is lower than the VBATT input voltage.

Watchdog Timer and Oscillator

The watchdog circuit monitors the activity of the microprocessor. If the microprocessor does not toggle the watchdog input (WDI) within the selected timeout period, a 50ms RESET pulse is generated. Since many systems cannot service the watchdog timer immediately after a reset, the MAX696/MAX697 have a longer timeout period after a reset is issued. The normal timeout period

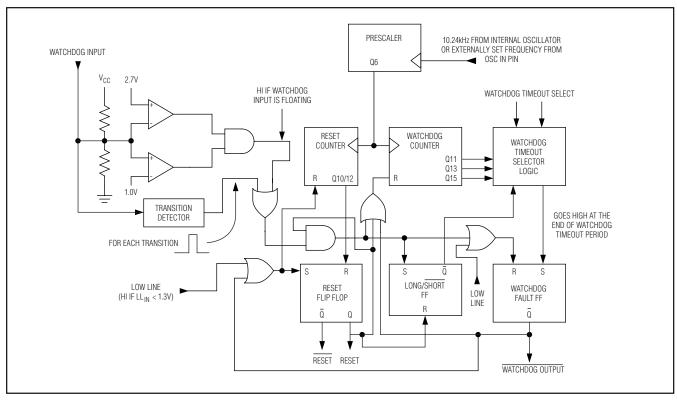


Figure 6. Watchdog Timer Block Diagram

becomes effective following the first transition of WDI after RESET has gone high. The watchdog timer is restarted at the end of reset, whether the reset was caused by lack of activity on WDI or by LL_{IN} falling below 1.3V. If WDI remains either high or low, reset pulses will be issued every 1.6s. The watchdog monitor can be deactivated by floating the watchdog input (WDI).

The watchdog output (WDO) goes low if the watchdog timer times out, and it remains low until set high by the next transition on the watchdog input. WDO is also set high when LLIN goes below 1.3V.

The watchdog timeout period defaults to 1.6s and the reset pulse width defaults to 50ms. The MAX696 and MAX697 allow these times to be adjusted per Table 1.

The internal oscillator is enabled when OSC SEL is high or floating. In this mode, OSC IN selects between the 1.6s and 100ms watchdog timeout periods. In either case, immediately after a reset, the timeout period is 1.6s. This gives the microprocessor time to reinitialize the system. WD transmissions while RESET is low are ignored. If OSC IN is low, then the 100ms watchdog period becomes effective after the first transition of WDI. The software should be written so the I/O port driving WDI is left in its power-up reset state until the initialization routines are completed and the microprocessor is able to toggle WDI at the minimum 70ms watchdog timeout period.

Applications Information

Adding Hysteresis to the Power-Fail Comparator

Since the power-fail comparator circuit is noninverting, hysteresis can be added by connecting a resistor between the PFO output and the PFI input as shown in Figure 7. When PFO is low, resistor R3 sinks current from the summing junction at the PFI pin. When PFO is high, the series combination of R3 and R4 source current into the PFI summing junction.

Alternate Watchdog Input Drive Circuits

The watchdog feature can be enabled and disabled under program control by driving WDI with a three-state

buffer (Figure 8). The drawback to this circuit is that a software fault may erroneously three-state the buffer, thereby preventing the MAX696/MAX697 from detecting that the microprocessor is no longer working. In most cases, a better method is to extend the watchdog period rather than disabling the watchdog. See Figure 9. When the control input is high, the OSC SEL pin is low and the watchdog timeout is set by the external capacitor. A 0.01µF capacitor sets a watchdog timeout delay of 100s. When the control input is low, the OSC SEL pin is driven high, selecting the internal oscillator. The 100ms or the 1.6s period is chosen, depending on which diode in Figure 9 is used.

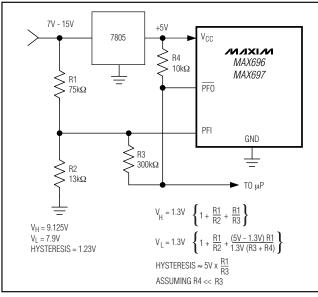


Figure 7. Adding Hysteresis to the Power-Fail Voltage Comparator

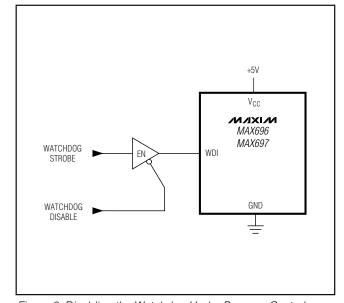


Figure 8. Disabling the Watchdog Under Program Control

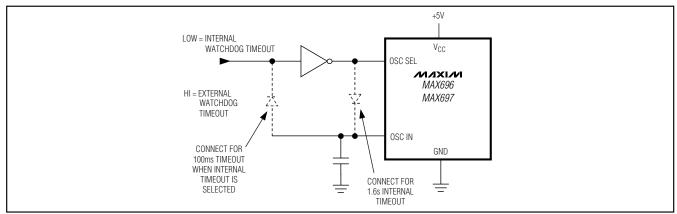


Figure 9. Selecting Internal or External Watchdog Timeout

Table 1. MAX696 and MAX697 Reset Pulse Width and Watchdog Timeout Selections (Notes 1, 2)

			WATCHDOG TIMEOUT PERIOD		
OSC SEL (Note 3)	OSC IN	NORMAL IMMEDIATELY AFTER RESET		RESET TIMEOUT PERIOD	
Low	External Clock Input	1024 clocks	4096 clocks	512 clocks	
Low	External Capacitor	400ms/47pF x C	1.6s/47pF x C	200ms/47pF x C	
High/Floating	Low	100ms	1.6s	50ms	
High/Floating	Floating	1.6s	1.6s	50ms	

Note 1: When the MAX696/MAX697 OSC SEL pin is low, OSC IN can be driven by an external clock signal, or an external capacitor can be connected between OSC IN and GND. The nominal internal oscillator frequency is 10.24kHz. The nominal oscillator frequency with external capacitor is fosc (Hz) = 184,000/Cosc (pF).

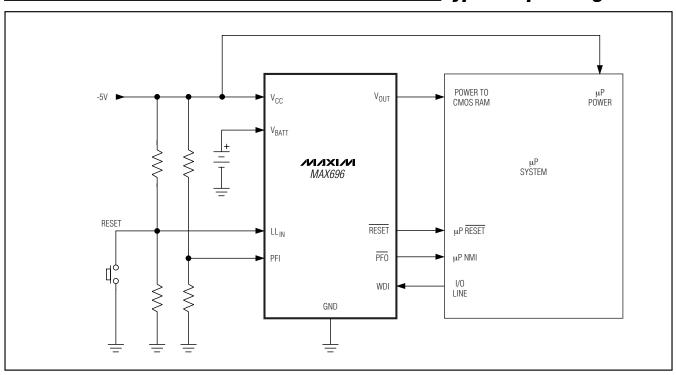
Note 2: See the *Electrical Characteristics* table for minimum and maximum timing values.

Note 3: High for the OSC SEL pin should be connected to V_{OUT}, not V_{CC} (on the MAX696).

Table 2. Input and Output Status in Battery-Backup Mode

I/O	STATUS	
VBATT, VOUT	V _{BATT} is connected to V _{OUT} with an internal MOSFET (MAX696 only).	
RESET	Logic-low.	
RESET	Logic-high. The open-circuit output voltage is equal to VOUT.	
LOW LINE	Logic-low.	
BATT ON	Logic-high (MAX696 only).	
WDI	WDI is internally disconnected from its internal pullup and does not source or sink current as long as its input voltage is between GND and V _{OUT} . The input voltage does not affect supply current.	
WDO	Logic-high.	
PFI	The power-fail comparator is turned off and the power-fail input voltage has no effect on the power-fail output.	
PFO	Logic-low.	
CE IN	$\overline{\text{CE}}$ IN is internally disconnected from its internal pullup and does not source or sink current as long as its input voltage is between GND and V _{OUT} . The input voltage does not affect supply current (MAX696 only).	
CE OUT	Logic-high (MAX697 only).	
OSC IN	OSC IN is ignored.	
OSC SEL	OSC SEL is ignored.	
Vcc	Approximately 12 μ A is drawn from the V _{BATT} input when V _{CC} is between (V _{BATT} + 100mV) and (V _{BATT} - 700mV). The supply current is 1 μ A maximum when V _{CC} is less than V _{BATT} - 700mV.	

Typical Operating Circuit

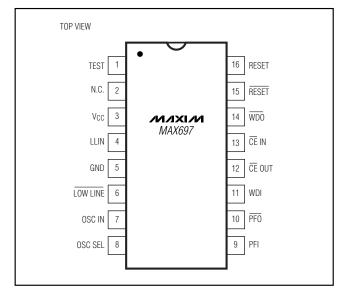


Ordering Information

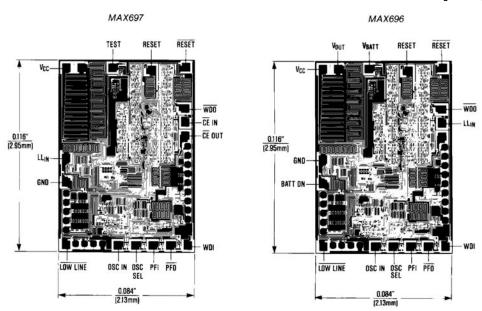
PART	TEMP RANGE	PIN-PACKAGE
MAX697C/D	0°C to +70°C	Dice
MAX697CPE	0°C to +70°C	16 PDIP
MAX697CWE	0°C to +70°C	16 Wide SO
MAX697EPE	-40°C to +85°C	16 PDIP
MAX697EJE	-40°C to +85°C	16 CERDIP
MAX697EWE	-40°C to +85°C	16 Wide SO
MAX697MJE	-55°C to +125°C	16 CERDIP

Devices in PDIP and SO packages are available in both leaded and lead-free packaging. Specify lead free by adding the + symbol at the end of the part number when ordering. Lead free not available for CERDIP package.

Pin Configurations (continued)



Chip Topography



Package Information

For the latest package outline information, go to www.maxim-ic.com/packages.

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